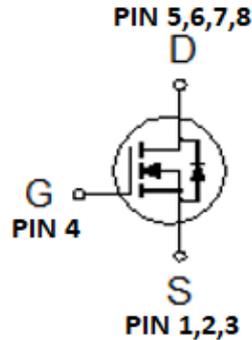


Single N-Channel Logic Level Enhancement Mode Field Effect Transistor

• Product Summary:

	N-CH
BV_{DSS}	30V
$R_{DSON (MAX.)@V_{GS}=10V}$	6.0m Ω
$R_{DSON (MAX.)@V_{GS}=4.5V}$	9.5m Ω
$I_D @T_C=25^\circ C$	44A

• Pin Description:



Single N Channel MOSFET

UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



• ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ C$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current ¹	$T_C = 25^\circ C$	I_D	44	A
	$T_A = 25^\circ C$		15	
	$T_C = 100^\circ C$		29	
Pulsed Drain Current ¹		I_{DM}	74	A
Avalanche Current ^{1,4}		I_{AS}	37	
Avalanche Energy ^{1,4}	$L = 0.1mH$	E_{AS}	68	mJ
Repetitive Avalanche Energy ^{2,4}	$L = 0.05mH$	E_{AR}	34.2	
Power Dissipation ¹	$T_C = 25^\circ C$	P_D	20.8	W
	$T_C = 100^\circ C$		8.3	
Power Dissipation ¹	$T_A = 25^\circ C$	P_D	2.3	W
	$T_A = 70^\circ C$		1.5	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	$^\circ C$

• 100% UIS testing in condition of $V_D=15V, L=0.1mH, V_G=10V, I_L=22A, \text{Rated } V_{DS}=30V \text{ N-CH}$

• THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		6	$^\circ C / W$
Junction-to-Ambient ³	$R_{\theta JA}$		55	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

³55 $^\circ C / W$ when mounted on a 1 in² pad of 2 oz copper.

⁴Guarantee by Engineering test

▪ ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage ⁴	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250uA	30			V
Gate Threshold Voltage ⁴	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	1.2	1.5	2.5	
Gate-Body Leakage ⁴	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current ⁴	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V			1	uA
		V _{DS} = 30V, V _{GS} = 0V, T _J = 125 °C			25	
On-State Drain Current ¹	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	44			A
Drain-Source On-State Resistance ^{1,4}	R _{DS(ON)}	V _{GS} = 10V, I _D = 14A		5	6	mΩ
		V _{GS} = 4.5V, I _D = 10A		7.5	9.5	
Forward Transconductance ¹	g _{fs}	V _{DS} = 5V, I _D = 14A		25		S
DYNAMIC						
Input Capacitance ⁵	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		1212		pF
Output Capacitance ⁵	C _{oss}			185		
Reverse Transfer Capacitance ⁵	C _{rss}			115		
Gate Resistance ^{4,5}	R _g	f = 1MHz		2	3.5	Ω
Total Gate Charge ^{1,2,5}	Q _g (V _{GS} =10V)	V _{DS} = 15V, V _{GS} = 10V, I _D = 14A		21.5		nC
	Q _g (V _{GS} =4.5V)			10.9		
Gate-Source Charge ^{1,2,5}	Q _{gs}			2.5		
Gate-Drain Charge ^{1,2,5}	Q _{gd}			4.3		
Turn-On Delay Time ^{1,2,5}	t _{d(on)}		V _{DS} = 15V, V _{GS} = 10V, I _D = 1A, R _g = 6Ω		6	
Rise Time ^{1,2,5}	t _r			5		
Turn-Off Delay Time ^{1,2,5}	t _{d(off)}			33		
Fall Time ^{1,2,5}	t _f			16		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS						
Continuous Current	I _S				44	A
Pulsed Current ³	I _{SM}				74	
Forward Voltage ^{1,4}	V _{SD}	I _F = I _S = 14A, V _{GS} = 0V			1.2	V
Reverse Recovery Time ⁵	t _{rr}	I _F = I _S = 24A, dI _F /dt = 400A / mS		7.65		nS
Peak Reverse Recovery Current ⁵	I _{RM(REC)}			1.99		A
Reverse Recovery Charge ⁵	Q _{rr}			8.17		nC

¹ Pulse test : Pulse Width ≤ 300 usec, Duty Cycle ≤ 2%.

² Independent of operating temperature.

³ Pulse width limited by maximum junction temperature.

⁴ Guarantee by FT test Item

⁵ Guarantee by Engineering test

EMC will review datasheet by quarter, and update new version.

▪ TYPICAL CHARACTERISTICS

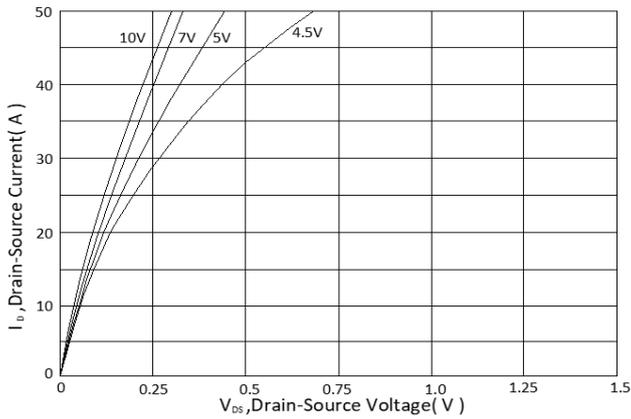


Fig.1 Typical Output Characteristics

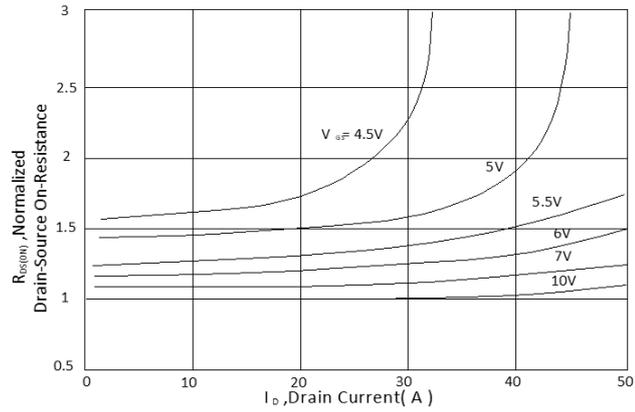


Fig.2 On-Resistance Variation with Drain Current and Gate Voltage

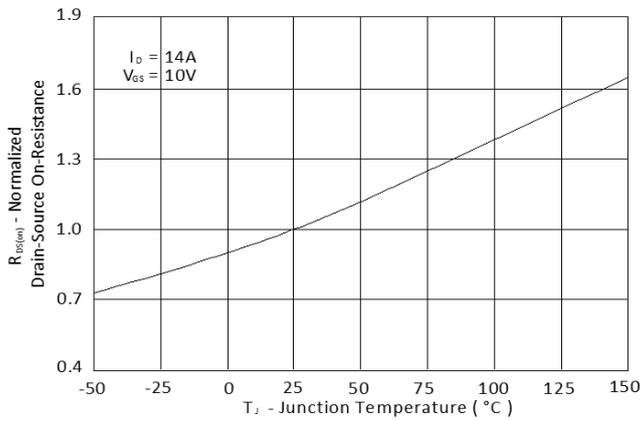


Fig.3 Normalized On-Resistance v.s. Junction Temperature

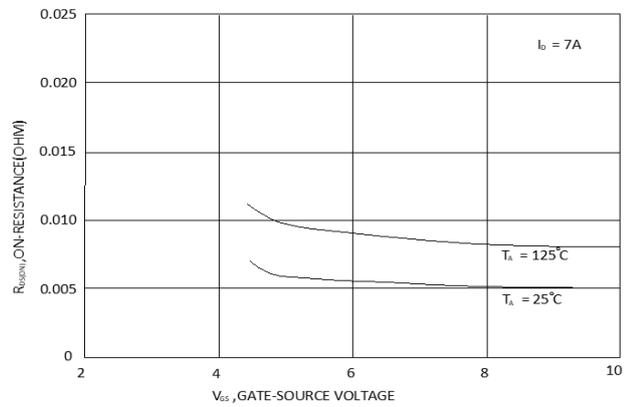


Fig.4 On-Resistance v.s. Gate Voltage

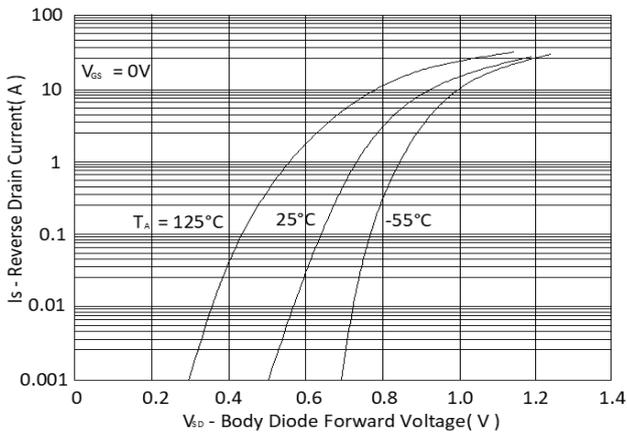


Fig.5 Forward Characteristic of Reverse Diode

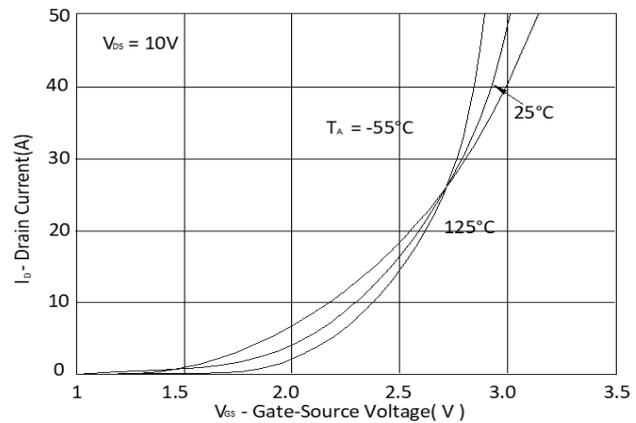


Fig.6 Transfer Characteristics

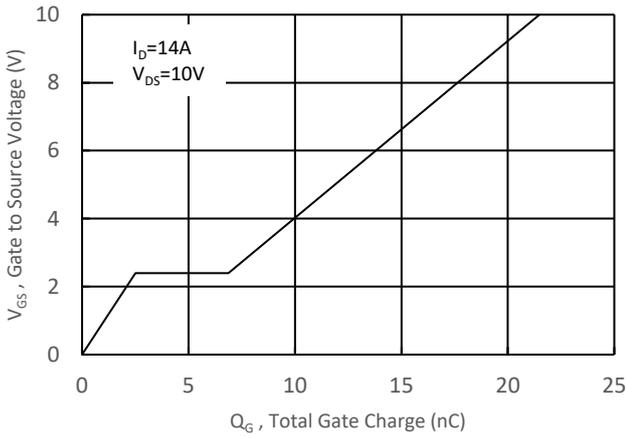


Fig. 7 Gate Charge Characteristics

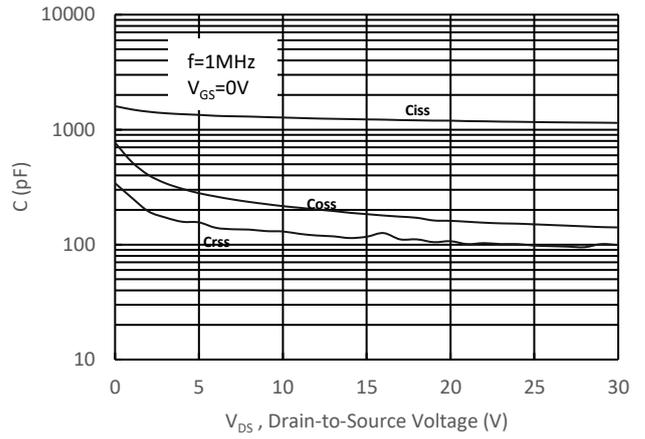


Fig.8 Typical Capacitance Characteristics

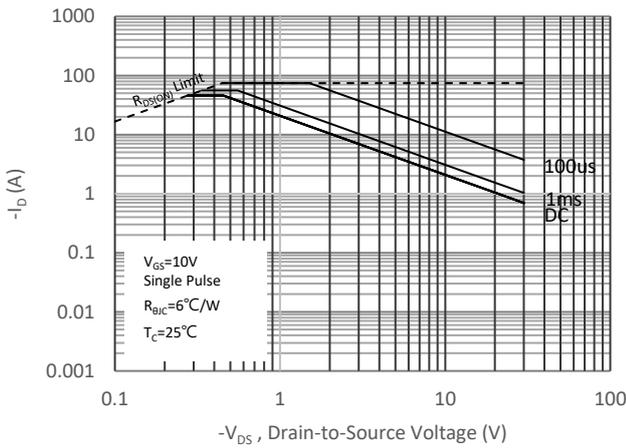


Fig 9. Maximum Safe Operating Area

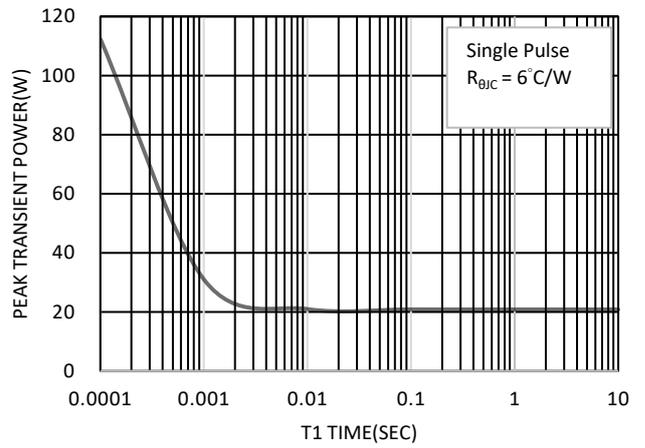


Fig 10. Single Pulse Maximum Power Dissipation

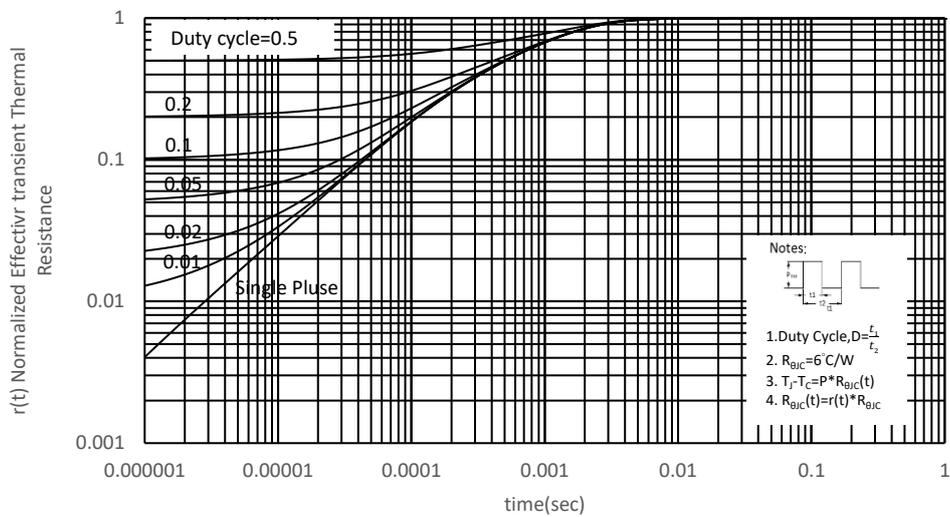
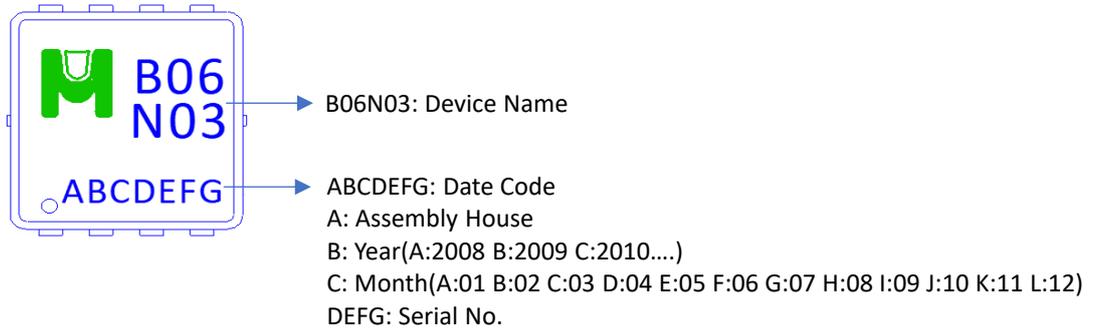


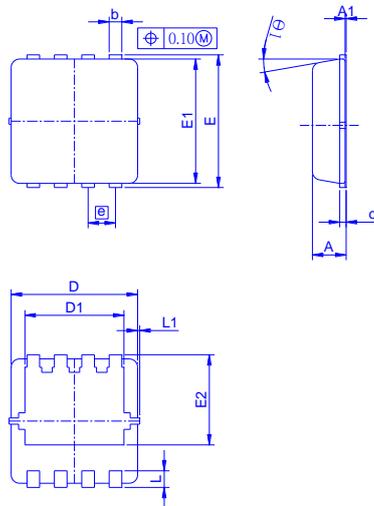
Fig 11. Effective Transient Thermal Impedance

Ordering & Marking Information:

Device Name: EMB06N03V for EDFN 3x3

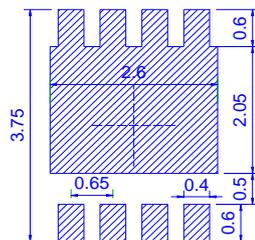


Outline Drawing

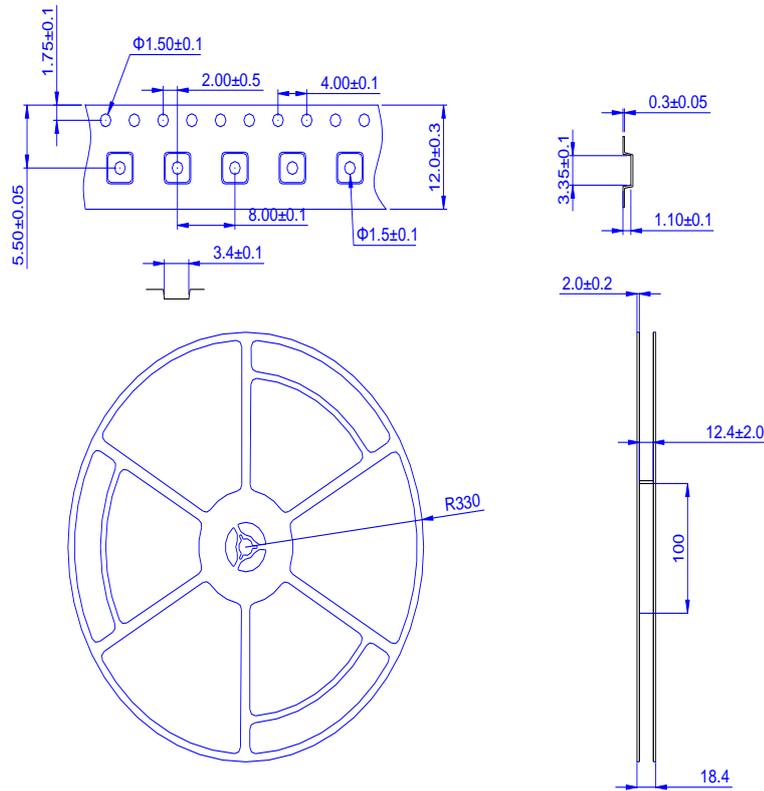


Dimension	A	A1	b	c	D	D1	E	E1	E2	e	L	L1	θ1
Min.	0.65	0	0.2	0.1	2.9	2.15	3.1	2.9	1.53	0.55	0.25	-	0°
Typ.	0.75	-	0.3	0.15	3	2.45	3.2	3	1.97	0.65	0.4	0.075	10°
Max.	0.9	0.05	0.4	0.25	3.3	2.74	3.5	3.3	2.59	0.75	0.6	0.15	14°

Footprint



◆ **Tape&Reel Information:5000pcs/Reel(Dimension in millimeter)**



產品別	EDFN 3x3
Reel尺寸	13"
編帶方式	<p>FEED DIRECTION</p>
前空格	50
後空格	50
裝箱數	
滿捲數量	5K
捲/內盒比	01:01
內盒滿箱數	5K
內/外箱比	10:01
外箱滿箱數	50K



★Datasheet Latest version specification :

	Revision History	Prepared	Approved	Date
A.0	Initial Datasheet	Jannie	Andy	2015/9/25
A.1	Add revision elements as required by Compal	Johnson	Andy	2019/10/23
A.2	Update thermal resistance coefficient and related information	Johnson	Sam	2020/6/29